Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company unique ID Unique ID Authority Response Date* 2024-05-10 2024-05-10 Contact Name Title - Contact Title - Contact Phone - Contact* Phone - Contact* Product-Env-Stewards NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Na Product-Env-Stewards Namufacturing Site Weight* UOM Wanufacturing Proccess Information Manufacturing Proccess Information Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 Seconds 3	752-21.1											als and Mf	g Informati	ion	
Semil	upplier Inform	ation				·									
Title - Contact Name Product Envisor Compliance NA Product Envisor Email - Representative* Product Envisor Compliance NA Product Envisor Email - Representative* Product Envisor Compliance NA Product Envisor Email - Representative* Product Envisor Compliance NA Product Envisor Email - Representative* Product Envisor Compliance NA Product Envisor Email - Representative* Product Envisor	Company name* Company unique				que ID Uni		Unique ID Authority				Response Date*				
Product Env-Stewards uthorized Representative* Title - Representative Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Phone - Representative* Product-Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com Product-Env-Stewards@onsemi.com NA	nsemi											2024-05-10			
Authorized Representative* Product-Env-Stewards Requester Item Number Mfr Item	ontact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product Envi-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Process Information Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM U LoN2 4.58939 mg Feak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds 3 Comments	Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represer	ntative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
MM3Z16VC 16.0V 0.2W 5% Zen SOD323F 2024-05-10 CN2 4.58939 mg I In a second solution and the second solution of the second solution is second solution. In the second solution is second solution in the second solution is second solution. In the second solution is second solution in the second solution is second solution. In the second solution is second solution in the second solution is second solution. In the second solution is second solution in the second solution is second solution. In the second solution is second solution in the second solution is second solution. In the second solution is second solution in the second solution is second solution in the second solution is second solution in the sec	Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Anufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Requester Item Number Mfr Ite		Number	Mfr Item Name			Effective Date	Version	N	Anufacturing Site	V	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			MM3Z16	5VC	16.0V 0.2W 5% Ze	en SOD323F		2024-05-10		C	CN2	4.	58939	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				Jarminal Paga	Alloy	CTD 020 MSI	Dating	Dook Prog	agg Pody To	maratur	May Time at Dook	Tomporatu	ra Numb	per of Poflow Cyc	Jac
omments	2 2			The state of the s		L Kanng							ber of Reflow Cyc	ties	
	•	i (Sii) - aimeaicu		O Alloy	1			1200		<u> </u> C	30	Second	s 3		
ver 1 - maximum time at peak temperature uning soldering is 10-50 seconds		ima at nools tomnors turn	during sel	doring is 10.3	0 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cornel to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to suc											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.0285	mg
			Supplier	Gold (Au)	7440-57-5		0.0014	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0001	mg
Lead Frame	1.004	mg	Supplier	Silver (Ag)	7440-22-4		0.004	mg
			Supplier	Chromium (Cr)	7440-47-3		0.002	mg
			Supplier	Manganese (Mn)	7439-96-5		0.008	mg
			В	Nickel (Ni)	7440-02-0		0.41	mg
			Supplier	Iron (Fe)	7439-89-6		0.58	mg
Mold Compound-Black	3.44999	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.3736	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0186	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.7179	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.3398	mg
Plating	0.1	mg	Supplier	Tin (Sn)	7440-31-5		0.1	mg
Wire Bond - Cu	0.0054	mg	Supplier	Copper (Cu)	7440-50-8		0.0054	mg